

Abstract

The invention is a method of forming an array of caps for attachment to a wafer which includes a plurality of microfabricated devices. The method includes sandwiching a sheet (134) of thermoplastic material between upper and lower molds (102, 104), heating
5 the sheet to a plastic state and molding the sheet into caps. The molds (102, 104) are preferably formed of silicon and infrared radiation is preferably used to heat the sheet (134).

1
2
3
4
5
6
7
8
9
10
11
12
13
14
15
16
17
18
19
20
21
22
23
24
25
26
27
28
29
30
31
32
33
34
35
36
37
38
39
40
41
42
43
44
45
46
47
48
49
50
51
52
53
54
55
56
57
58
59
60
61
62
63
64
65
66
67
68
69
70
71
72
73
74
75
76
77
78
79
80
81
82
83
84
85
86
87
88
89
90
91
92
93
94
95
96
97
98
99
100